

# SEGR/SEB Radiation test Method Study

## Presentation of Results & Analysis following Heavy ions Irradiations

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A. CARVALHO\*, Ch. BINOIS\*, R. MANGERET\*, M. MARINONI\*  
& V. FERLET-CAVROIS\*\*

\* EADS-ASTRIUM SAS

\*\* ESA/ESTEC

Presentation to CNES/ESA Days

( March, 29<sup>th</sup> 2011)

All the space you need



# Description of the study

- To study Post-Irradiation Gate Stress Test (PIGST) method for SEGR characterization through electrical and heavy ion testing
  1. Characterization of studied devices for SEGR under heavy ion beam and during PIGST
  2. Investigation of 3 different approaches for Gate Stress
    - PIGS
    - Time To Breakdown (TTBD)
    - and Charge To Breakdown (QTBD)
  3. Study of the breakdown behaviour of devices through accurate measurements
  4. Correlation of observed failures during PIGST and during heavy ion irradiation
- Two different N-channel MOSFET types selected

Part Type	2SK4219 (FUJI)
Characteristics	100V N-Channel
Package	SMD0.5
Die area	~12 mm <sup>2</sup>
Gate oxide thickness	not provided

Part Type	HG0K (STM)
Characteristics	100V N-Channel
Package	T0-3
Die area	29 mm <sup>2</sup>
Gate oxide thickness	47nm

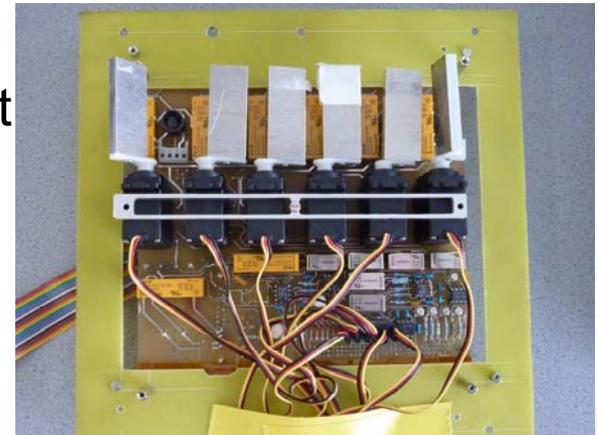
## Chronological events

- May 2009: Kick-off
- June 2009 : 1<sup>st</sup> HI testing at UCL facility
- May 2010: Follow-on meeting on ESA premises
- June 2010: Key personnel replacement
- July 2010: 2<sup>nd</sup> HI testing at UCL facility
- April 2011: Laser testing at ASTRIUM-IW facility
- ~May-June 2011: 3<sup>rd</sup> HI testing at UCL facility

# Experimental setup presentation (1/5)

## ■ The original setup

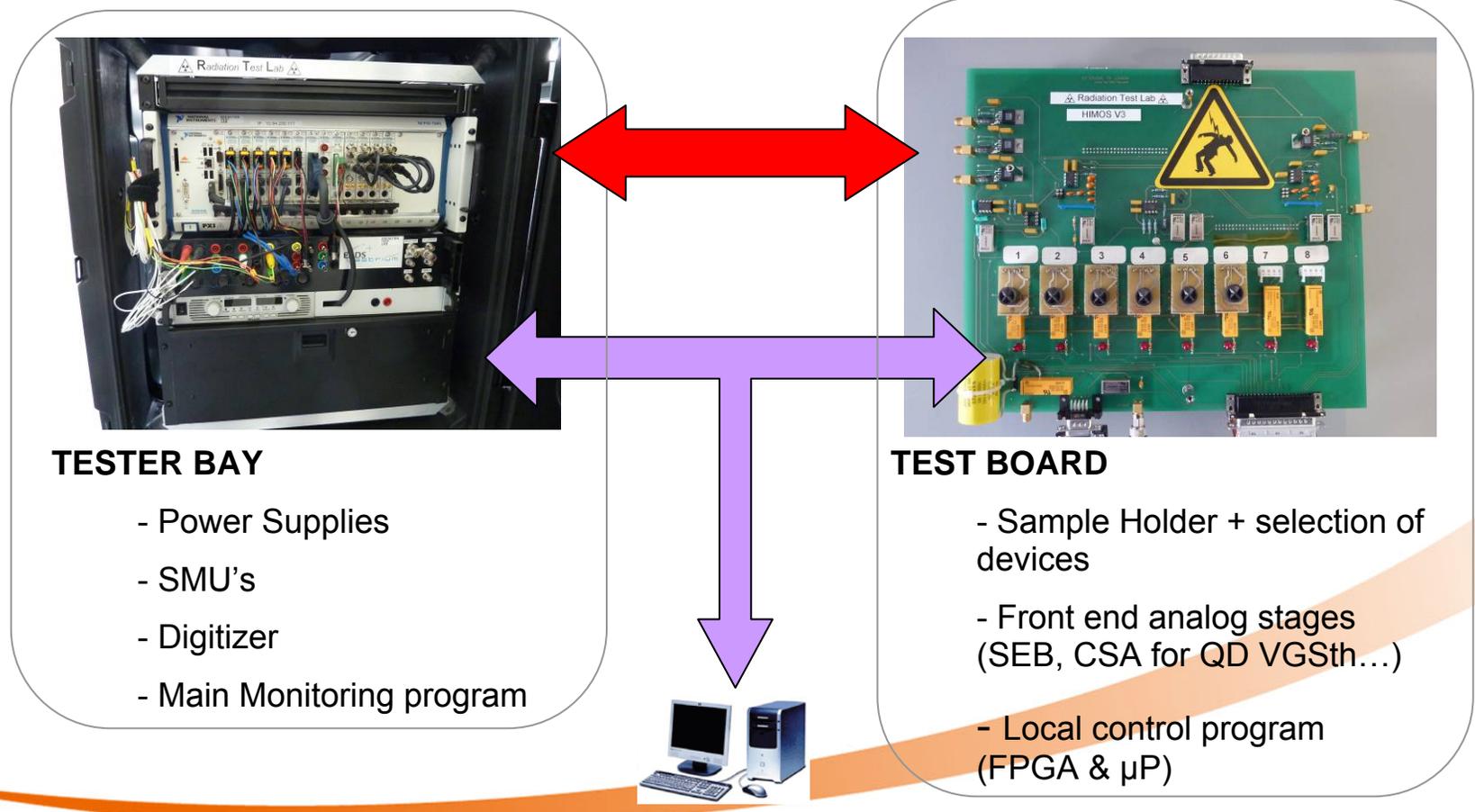
- was designed in 2004
- was used for the 1<sup>st</sup> test campaign in June 2009
- needs to be improved for
  - ✓ a better accuracy on Igss measurement
  - ✓ drain charge collection detection
  - ✓ Vgsth measurement
  - ✓ IDss on line
  - ✓ PIGS range increase



- A new Test setup has been developed and used during the 2<sup>nd</sup> irradiation campaign in July 2010

# Experimental setup presentation (2/5)

## ■ New Test setup description



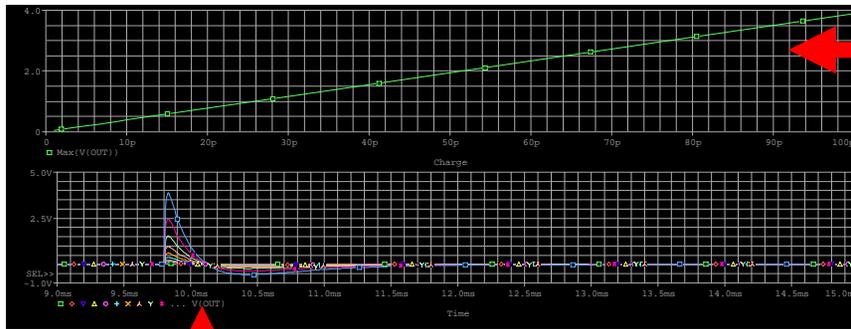
# Experimental setup presentation (3/5)

## ■ Test system characteristics

- 8 test slots
- Can hold P and N channel up to 600V Vds and +/-100V Vgs
- On line measurement of Igss (10pA to 100mA) and Idss
- SEB detection and Drain charge collection integrated acquisitions
- Integrated Vgsth measurement for N channel (P to be added)
- Embedded Processor and FPGA (RTOS for short time response and local tasks management)
- Remote controlled operation
- Integrated autotest to check device and tester integrity before irradiation ( **a not connected device is seen insensitive** )

# Experimental setup presentation (4/5)

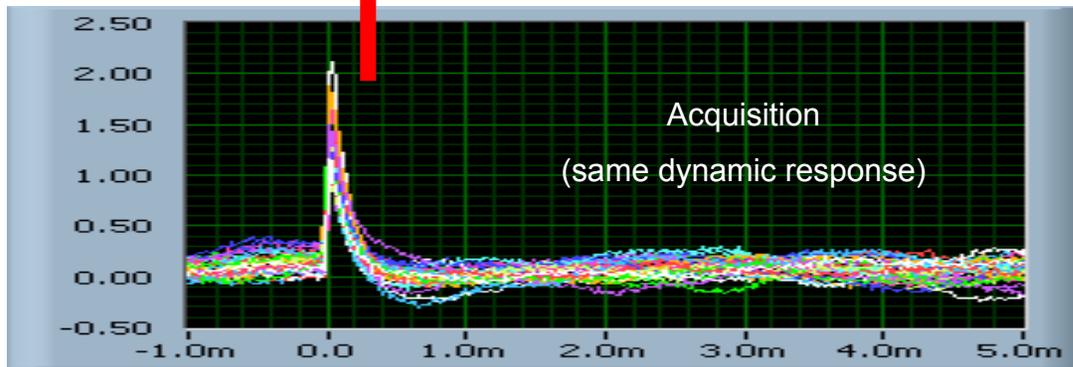
- Focus on Integrated charge collection system



Pspice Simulation

Theoretical conversion ratio  
40mV/pC

To be calibrated by comparison with  
ESA test setup by using EADS IW  
Laser test bench



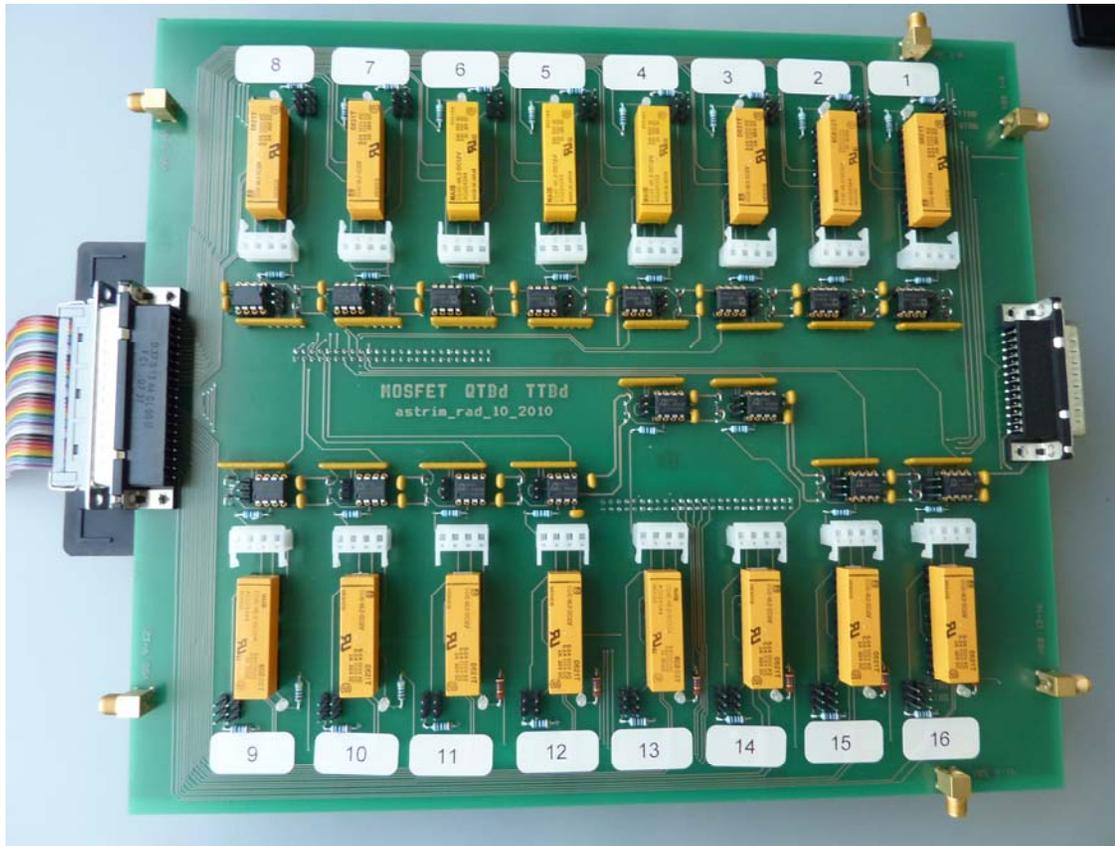
Low Frequency noise is coming from the Drain supply

*\*\* Good indicator to  
check if device is really  
irradiated*

*Works also for P  
channel*

# Experimental setup presentation (5/5)

## ■ QTBD & TTBD board



16 test slots

Visual information for  
device health state

QTBD or TTBD selectable  
per slot

# Experimental Results from WP2100

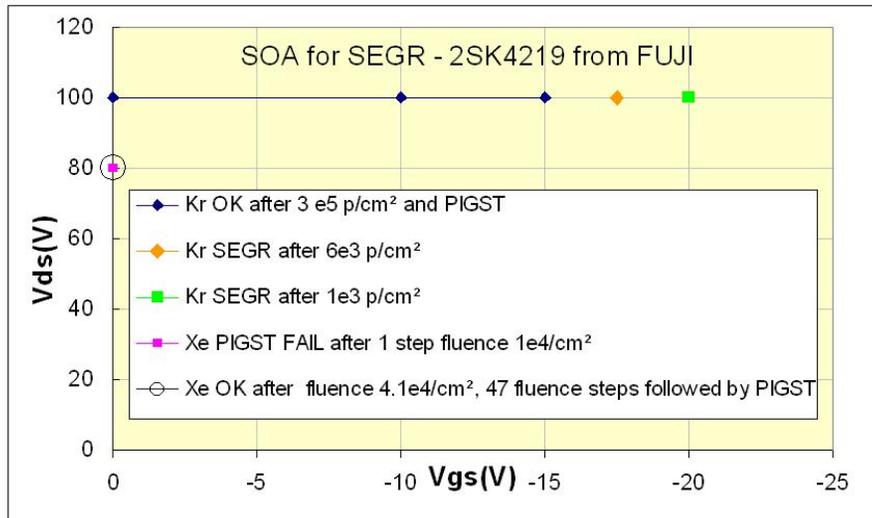
- ✓ Characterization of SOA for SEGR

# Experimental Results from WP2100

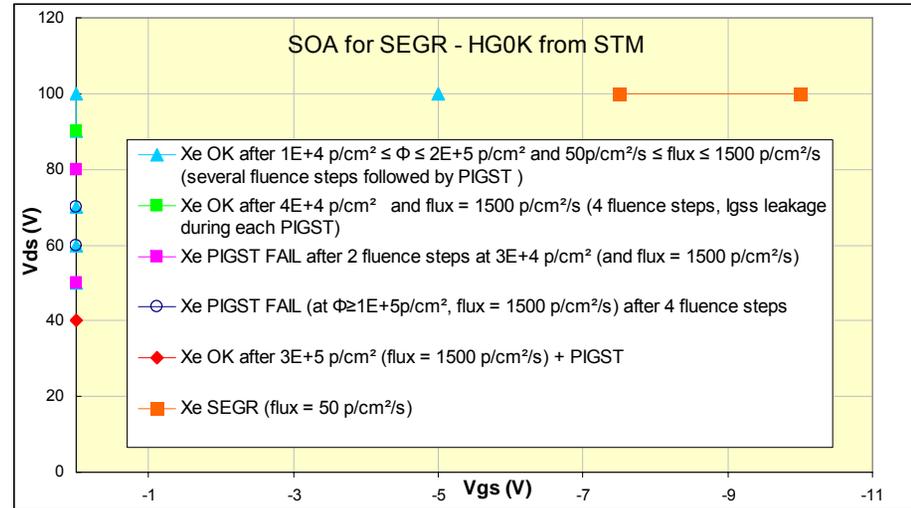
- 1<sup>st</sup> irradiation test campaign performed at UCL facility

Heavy Ion specie	HI energy [MeV]	Range [ $\mu\text{m Si}$ ]	LET [MeV.mg.cm <sup>-2</sup> ]
<sup>83</sup> Kr <sup>25+</sup>	756	92.0	31.0
<sup>132</sup> Xe <sup>26+</sup>	459	43.0	67.7

- Characterization of SOA for SEGR



2SK4219 (FUJI)



HG0K (STM)

SEGR or PIGS failure observed only for fluences higher than 1E+4 p/cm<sup>2</sup> : Multiple impacts suspected  
 → “SEGR Study on Power MOSFETs: Multiple Impacts Assumption” D. Peyre *et al.*, *IEEE TNS Vol 55, Iss 4*, pp.

2181-2187, 2008

# Experimental Results from WP2200

- ✓ Intrinsic breakdown voltage assessment
- ✓ Charge collection at drain level measurement

# Experimental Results from WP2200 (1/7)

- 2<sup>nd</sup> irradiation test campaign performed at UCL facility

<i>Heavy Ion specie</i>	<i>HI energy [MeV]</i>	<i>Range [<math>\mu\text{m Si}</math>]</i>	<i>LET [<math>\text{MeV}\cdot\text{mg}\cdot\text{cm}^{-2}</math>]</i>
$^{132}\text{Xe}^{26+}$	459	43.0	67.7

- Intrinsic breakdown voltage of the gate oxide assessment (1/3)

PIGST evolution at higher voltage levels explored until gate rupture occurred. PIGS test repeated by increasing the maximum voltage (in + and - polarity) in small steps

➡ Voltage threshold for leakage current onset is much higher than spec limit of device (20V)

# Experimental Results from WP2200 (2/7)

- Intrinsic breakdown voltage of the gate oxide assessment (2/3)

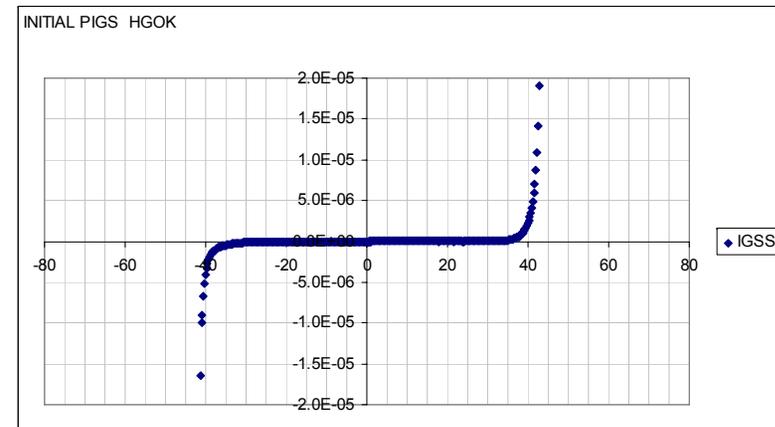
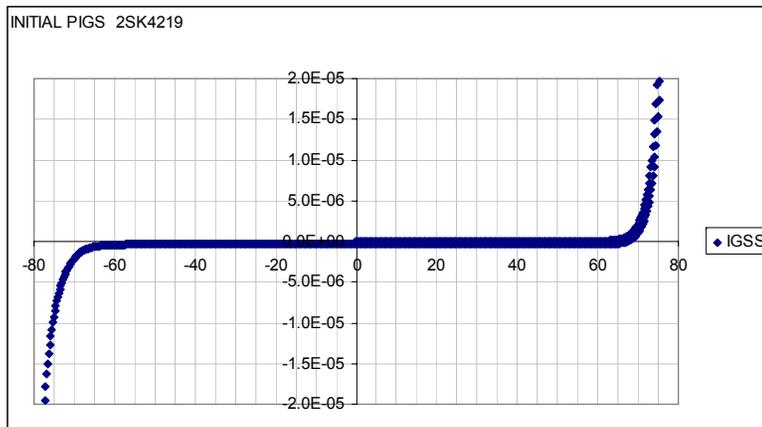
➔ Extended PIGS levels defined after this evaluation:

	2SK4219	HG0K
Standard specification	$V_{gs} = +20V/-20V$	$V_{gs} = +20V/-20V$
Experimental Target Leakage onset (+100nA/-100nA)	$V_{gs} = +60V/-45V$	$V_{gs} = +30V/-24V$
Experimental Target limit leakage	$V_{gs} = +65V/-60V$ Typical current 200nA/-300nA	$V_{gs} = +36V/-30V$ Typical current 100nA/-120nA

# Experimental Results from WP2200 (3/7)

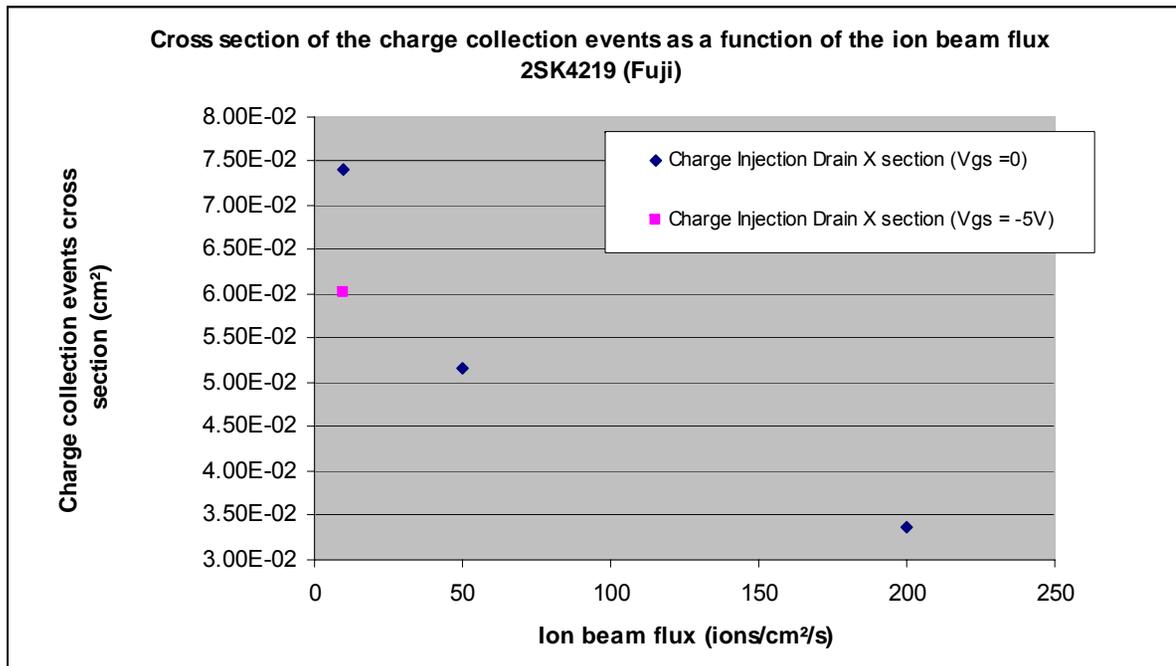
- Intrinsic breakdown voltage of the gate oxide assessment (3/3)

➔ Fuji parts have far higher intrinsic breakdown voltage ( $V_{bd}$ ) than STM parts



# Experimental Results from WP2200 (4/7)

## ■ Charge Collection at Drain Level: Flux Effect (1/3)



➔ Limiting the flux below 50 ions.cm<sup>-2</sup>.s<sup>-1</sup> gives a reasonable detection ratio of the charge collection events

# Experimental Results from WP2200 (5/7)

## Charge Collection at Drain Level: Flux Effect (2/3)

➔ The lower the flux, the higher the charge collection events cross section

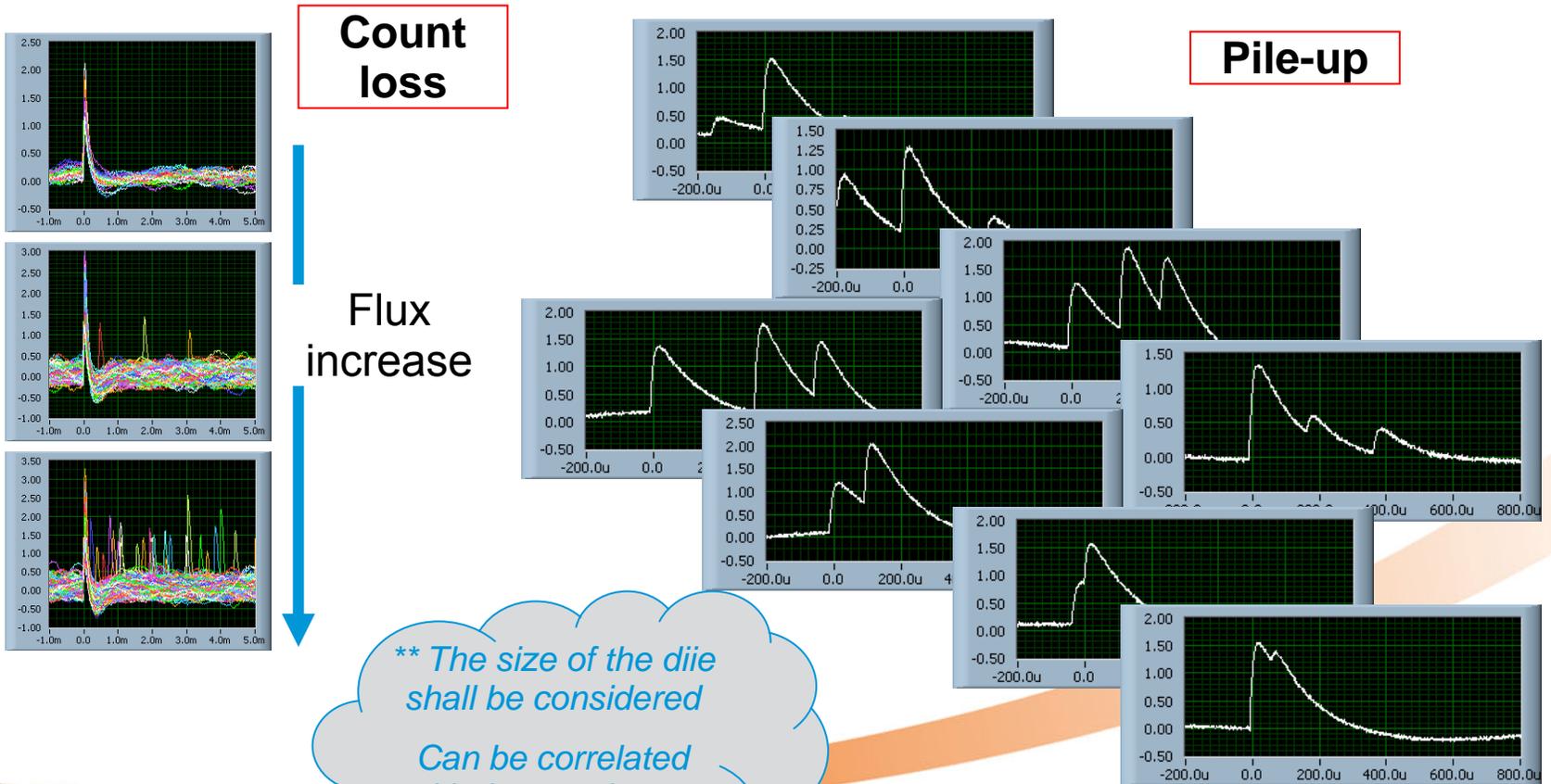
➔ Even in over-blocking condition on Vgs, charge collection measurement is still possible

EADS-ASTRIUM																						
test	SEE sensitivity			default Xsection																5.00E-07	5.00E-07	5.00E-07
comp	MOS_STM	VDS Max Rating	100 V																			
Type	N																					
															Charge Injection Drain		SEB		SEGR			
Run	devices	Ion	LET (MeV cm <sup>2</sup> /mg)	Range (µm)	Flux (p/cm <sup>2</sup> /s)	Fluence (f/cm <sup>2</sup> )	Vgsth_p rérad (V)	Vgsth_p ostrad (V)	Vds (V)	Vgsoff	PIGS_post rad	Vgs(V) @ PIGS failure	Trigg (V)	Nb events GBD	X section	Nb events	X section	Nb events	X section			
36	205	132 Xe 26+	67.7	43	8	9.4E+03	3.553	3.524	80	0V	OK	-		1000	1.06E-01		5.00E-07		5.00E-07			
37	206	132 Xe 26+	67.7	43	15	5.0E+03	3.476	3.455	80	0V	OK	-		552	1.10E-01		5.00E-07		5.00E-07			
38	207	132 Xe 26+	67.7	43	15	5.0E+03	3.407	3.526	80	0V	OK	-		595	1.19E-01		5.00E-07		5.00E-07			

➔ Confirmation with STM parts that fluxes below 50 ions.cm<sup>-2</sup>.s<sup>-1</sup> give reasonable detection ratio of the charge collection events

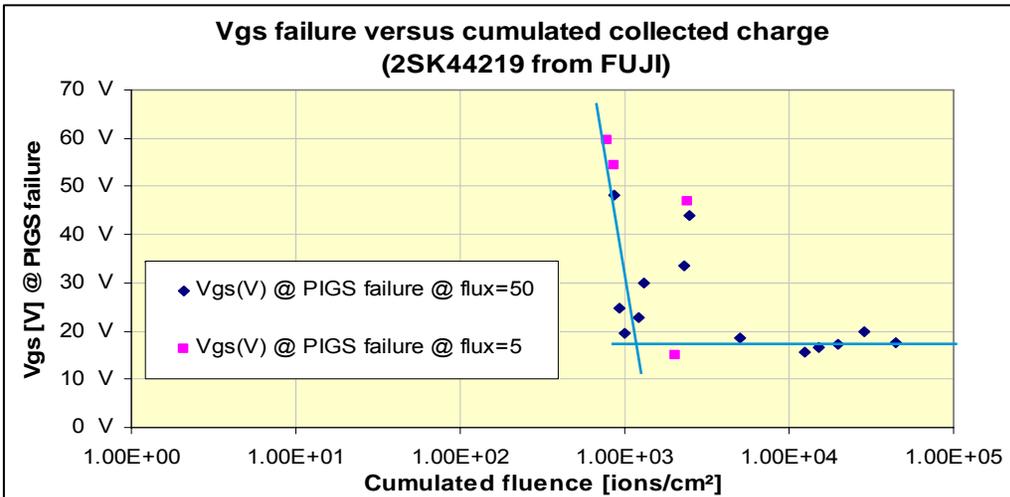
# Experimental Results from WP2200 (6/7)

- Charge Collection at Drain Level: Flux Effect (3/3)
  - 2 Probable causes of issue



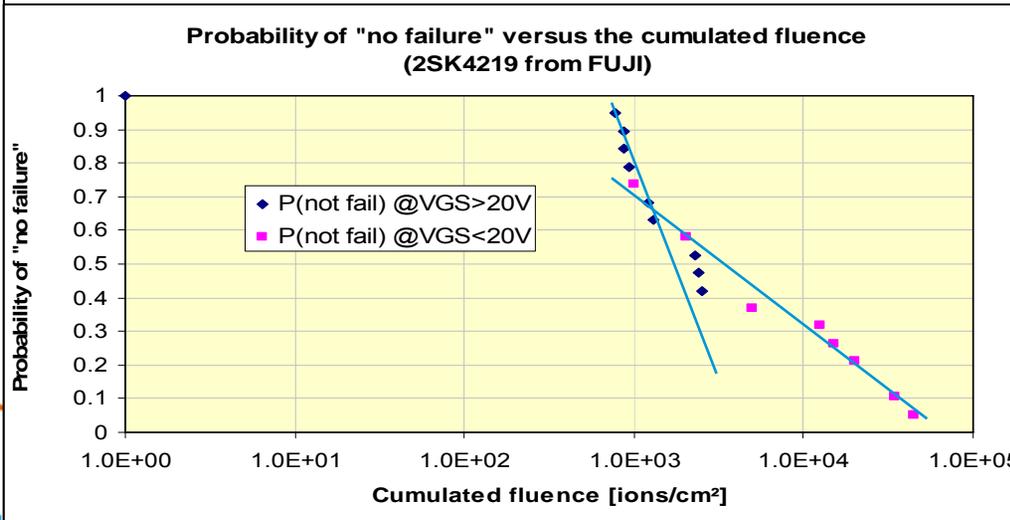
# Experimental Results from WP2200 (7/7)

## Breakdown Vgs during PIGST: Fluence Effect



lower fluences  $\longleftrightarrow$  higher Vgs failure during PIGST

$\Phi < 5E+3$  ions.cm<sup>-2</sup>  $\longleftrightarrow$  Vgs failure during PIGST  $\geq 20V$



$\longrightarrow$  The higher the fluence, the higher the probability of failure during PIGST

$\longrightarrow$  Needs a deeper statistical analysis

# Conclusion

- Extended PIGS levels have been defined and leakage current onset determined
- Charge collection at drain level can be used as a smart checking tool during irradiation (Beam presence, characteristics and dosimetry check )
- Charge collection at drain level can be used also under over-blocking conditions
- Breakdown  $V_{gs}$  during PIGST depends on cumulated fluence (*Multiple impact suspected*)

## Work to be performed

- Completion of SOA for SEGR
- QBD and TBD tests on irradiated parts and pristine parts (as reference)
- Intrinsic breakdown voltage versus breakdown voltage during PIGST: is there a link?
- Laser testing (Charge collection circuit calibration)
- Confirm the results by a statistical study